



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Application of:

Hidehiko KIRA et al.

Serial Number: 08/897,953

Group Art Unit: 1107

Filed: July 24, 1997

Examiner: David E. GRAYBILL

For: METHOD AND APPARATUS FOR FABRICATING SEMICONDUCTOR DEVICE

AMENDMENT UNDER 37 CFR §1.115

Assistant Commissioner of Patents  
Washington, D.C. 20231

RECEIVED  
GROUP 210  
April 16, 1998

Sir:

In response to the Office Action dated December 16, 1997, please amend the above-identified application as follows:

IN THE SPECIFICATION:

Page 11, line 14, delete "and the half-thermosetting process on the insulating adhesive".<sup>1</sup>

IN THE CLAIMS:

Please cancel claims 1, 2 and 7 without prejudice or disclaimer.

<sup>1</sup> Please see, also, lines 3 - 5, page 2 of the Amendment under 37 CFR §1.115 filed on August 16, 1996.